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(19) **United States**(12) **Patent Application Publication****Karakawa et al.**(10) **Pub. No.: US 2022/0386468 A1**(43) **Pub. Date:****Dec. 1, 2022**(54) **SEMICONDUCTOR MODULE AND
ELECTRONIC APPARATUS**(52) **U.S. CL.**CPC **H05K 1/181** (2013.01); **H01L 23/49816**
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A semiconductor module includes a semiconductor device having a first land, a second land, and a third land, a wiring board having a substrate, and a fourth land, a fifth land, and a sixth land disposed on the main surface of the substrate, a chip component having a first electrode and a second electrode disposed across a distance in the longitudinal direction and being disposed between the wiring board and the semiconductor device, a first solder joint for bonding the first land, the fourth land, and the first electrode, a second solder joint for bonding the second land, the fifth land, and the second electrode, and a third solder joint for bonding the third land and the sixth land. The volume of the first solder joint and the volume of the second solder joint are each larger than the volume of the third solder joint.

